

March 2002 Revised June 2002

# 74LVT32245 • 74LVTH32245 Low Voltage 32-Bit Transceiver with 3-STATE Outputs

#### **General Description**

The LVT32245 and LVTH32245 contain thirty-two non-inverting bidirectional buffers with 3-STATE outputs and are intended for bus oriented applications. The devices are byte controlled. Each byte has separate control inputs which can be shorted together for full 32-bit operation. The  $T/\overline{R}$  inputs determine the direction of data flow through the device. The  $\overline{OE}$  inputs disable both the A and B ports by placing them in a high impedance state.

The LVTH32245 data inputs include bushold, eliminating the need for external pull-up resistors to hold unused inputs

These non-inverting transceivers are designed for low voltage (3.3V)  $V_{\rm CC}$  applications, but with the capability to provide a TTL interface to a 5V environment. The LVT32245 and LVTH32245 are fabricated with an advanced BiCMOS technology to achieve high speed operation similar to 5V ABT while maintaining low power dissipation.

#### **Features**

- Input and output interface capability to systems at 5V V<sub>CC</sub>
- Bushold data inputs eliminate the need for external pull-up resistors to hold unused inputs (74LVTH32245), also available without bushold feature (74LVT32245).
- Live insertion/extraction permitted
- Power Up/Down high impedance provides glitch-free bus loading
- Outputs source/sink -32 mA/+64 mA
- ESD performance:

Human-body model > 2000V

Machine model > 200V

Charged-device model > 1000V

Packaged in plastic Fine-Pitch Ball Grid Array (FBGA)

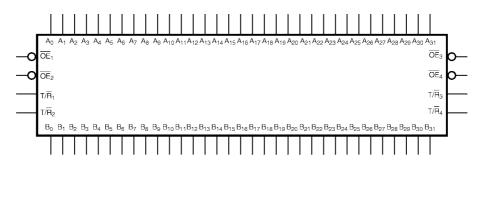
#### Ordering Code:

Order Number	Package Number	Package Description
74LVT32245G (Note 1)(Note 2)	BGA96A (Preliminary)	96-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide
74LVTH32245G (Note 1)(Note 2)	BGA96A	96-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide

Note 1: Ordering code "G" indicates Trays.

Note 2: Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code

#### **Logic Symbol**



### **Connection Diagram**

(Top Thru View)

### **Pin Descriptions**

Pin Names	Description
<del>OE</del> <sub>n</sub>	Output Enable Input (Active LOW)
T/R <sub>n</sub>	Transmit/Receive Input
A <sub>0</sub> -A <sub>31</sub>	Side A Inputs/3-STATE Outputs
B <sub>0</sub> -B <sub>31</sub>	Side B Inputs/3-STATE Outputs

### **FBGA Pin Assignments**

		1	2	3	4	5	6
	Α	B <sub>1</sub>	B <sub>0</sub>	T/R <sub>1</sub>	ŌE <sub>1</sub>	A <sub>0</sub>	A <sub>1</sub>
	В	В3	B <sub>2</sub>	GND	GND	A <sub>2</sub>	A <sub>3</sub>
	С	B <sub>5</sub>	B <sub>4</sub>	V <sub>CC1</sub>	$V_{CC1}$	A <sub>4</sub>	A <sub>5</sub>
	D	B <sub>7</sub>	В <sub>6</sub>	GND	GND	A <sub>6</sub>	A <sub>7</sub>
	E	B <sub>9</sub>	B <sub>8</sub>	GND	GND	A <sub>8</sub>	A <sub>9</sub>
	F	B <sub>11</sub>	B <sub>10</sub>	V <sub>CC1</sub>	$V_{CC1}$	A <sub>10</sub>	A <sub>11</sub>
	G	B <sub>13</sub>	B <sub>12</sub>	GND	GND	A <sub>12</sub>	A <sub>13</sub>
	Н	B <sub>14</sub>	B <sub>15</sub>	T/R <sub>2</sub>	OE <sub>2</sub>	A <sub>15</sub>	A <sub>14</sub>
b	J	B <sub>17</sub>	B <sub>16</sub>	T/R <sub>3</sub>	OE <sub>3</sub>	A <sub>16</sub>	A <sub>17</sub>
1	K	B <sub>19</sub>	B <sub>18</sub>	GND	GND	A <sub>18</sub>	A <sub>19</sub>
	L	B <sub>21</sub>	B <sub>20</sub>	$V_{CC2}$	$V_{CC2}$	A <sub>20</sub>	A <sub>21</sub>
	M	B <sub>23</sub>	B <sub>22</sub>	GND	GND	A <sub>22</sub>	A <sub>23</sub>
	N	B <sub>25</sub>	B <sub>24</sub>	GND	GND	A <sub>24</sub>	A <sub>25</sub>
	Р	B <sub>27</sub>	B <sub>26</sub>	$V_{CC2}$	$V_{CC2}$	A <sub>26</sub>	A <sub>27</sub>
	R	B <sub>29</sub>	B <sub>28</sub>	GND	GND	A <sub>28</sub>	A <sub>29</sub>
	Т	B <sub>30</sub>	B <sub>31</sub>	$T/\overline{R}_4$	$\overline{OE}_4$	A <sub>31</sub>	A <sub>30</sub>

# **Truth Tables**

Inputs		0.11.11			
OE <sub>1</sub> T/R <sub>1</sub>		Outputs			
L	L	Bus B <sub>0</sub> –B <sub>7</sub> Data to Bus A <sub>0</sub> –A <sub>7</sub>			
L	Н	Bus A <sub>0</sub> –A <sub>7</sub> Data to Bus B <sub>0</sub> –B <sub>7</sub>			
Н	Х	HIGH–Z State on A <sub>0</sub> –A <sub>7</sub> ,B <sub>0</sub> –B <sub>7</sub>			

Inp	uts	Outrote				
OE <sub>2</sub>	T/R <sub>2</sub>	Outputs				
L	L	Bus B <sub>8</sub> –B <sub>15</sub> Data to Bus A <sub>8</sub> –A <sub>15</sub>				
L	Н	Bus A <sub>8</sub> –A <sub>15</sub> Data to Bus B <sub>8</sub> –B <sub>15</sub>				
Н	Х	HIGH–Z State on A <sub>8</sub> –A <sub>15</sub> ,B <sub>8</sub> –B <sub>15</sub>				

H = HIGH Voltage Level L = LOW Voltage Level X = Immaterial

Inputs		0.4.4.				
OE <sub>3</sub>	T/R <sub>3</sub>	Outputs				
L	L	Bus B <sub>16</sub> –B <sub>23</sub> Data to Bus A <sub>16</sub> –A <sub>23</sub>				
L	Н	Bus A <sub>16</sub> –A <sub>23</sub> Data to Bus B <sub>16</sub> –B <sub>23</sub>				
Н	Х	HIGH–Z State on A <sub>16</sub> –A <sub>23</sub> ,B <sub>16</sub> –B <sub>23</sub>				

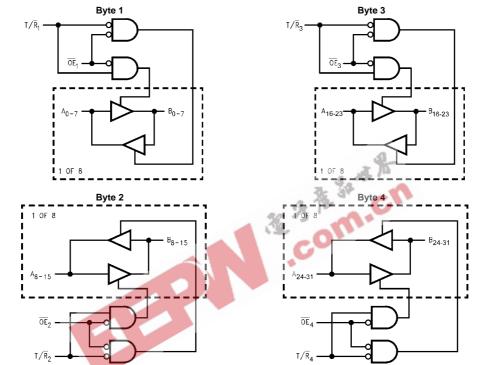
Inp	uts	2 1 1
ŌE <sub>4</sub>	T/R <sub>4</sub>	Outputs
L	L	Bus B <sub>24</sub> –B <sub>31</sub> Data to Bus A <sub>24</sub> –A <sub>31</sub>
L	Н	Bus B <sub>24</sub> –A <sub>31</sub> Data to Bus B <sub>24</sub> –B <sub>31</sub>
Н	Х	HIGH-Z State on Asa-Asa, Boa-Boa

Z = High Impedance

### **Functional Description**

The LVT32245 and LVTH32245 contain thirty-two non-inverting bidirectional buffers with 3-STATE outputs. The device is byte controlled with each byte functioning identically, but independent of the other. The control pins can be shorted together to obtain 16-bit or full 32-bit operation.

### **Logic Diagrams**



 $V_{\text{CC1}}$  is associated with Bytes 1 and 2.

 $V_{\text{CC2}}$  is associated with Bytes 3 and 4.

Note: Please note that these diagrams are provided only for the understanding of logic operations and should not be used to estimate propagation delays.

# **Absolute Maximum Ratings**(Note 3)

Symbol	Parameter	Value	Conditions	Units
V <sub>CC</sub>	Supply Voltage	-0.5 to +4.6		V
VI	DC Input Voltage	-0.5 to +7.0		V
Vo	Output Voltage	-0.5 to +7.0	Output in 3-STATE	V
		-0.5 to +7.0	Output in HIGH or LOW State (Note 4)	v
I <sub>IK</sub>	DC Input Diode Current	-50	V <sub>I</sub> < GND	mA
I <sub>OK</sub>	DC Output Diode Current	-50	V <sub>O</sub> < GND	mA
Io	DC Output Current	64	Output at HIGH State, V <sub>O</sub> > V <sub>CC</sub>	mA
		128	Output at LOW State, V <sub>O</sub> > V <sub>CC</sub>	1111/4
I <sub>CC</sub>	DC Supply Current per Supply Pin	±64		mA
I <sub>GND</sub>	DC Ground Current per Ground Pin	±128		mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150		°C

# **Recommended Operating Conditions**

Symbol	Parameter	Min 🚕	Max	Units
V <sub>CC</sub>	Supply Voltage	2.7	3.6	V
V <sub>I</sub>	Input Voltage	0	5.5	V
I <sub>OH</sub>	HIGH-Level Output Current	7	-32	mA
I <sub>OL</sub>	LOW-Level Output Current		64	mA
T <sub>A</sub>	Free-Air Operating Temperature	-40	+85	°C
Δt/ΔV	Input Edge Rate, V <sub>IN</sub> = 0.8V-2.0V, V <sub>CC</sub> = 3.0V	0	10	ns/V

Note 3: Absolute Maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum rated conditions is not implied.

Note 4: Io Absolute Maximum Ratings must be observed.

# **DC Electrical Characteristics**

Compleal	Parameter Parameter		V <sub>CC</sub>	$T_A = -40^{\circ}C$ to $+85^{\circ}C$		Units	Odistance
Symbol	Parame	ter	(V)	Min	Max	Units	Conditions
V <sub>IK</sub>	Input Clamp Diode Voltage		2.7		-1.2	V	I <sub>I</sub> = -18 mA
V <sub>IH</sub>	Input HIGH Voltage		2.7-3.6	2.0		V	V <sub>O</sub> ≤ 0.1V or
V <sub>IL</sub>	Input LOW Voltage		2.7-3.6		0.8	V	$V_O \ge V_{CC} - 0.1V$
√он	Output HIGH Voltage		2.7-3.6	V <sub>CC</sub> - 0.2			$I_{OH} = -100 \mu\text{A}$
		Ī	2.7	2.4		V	$I_{OH} = -8 \text{ mA}$
			3.0	2.0			$I_{OH} = -32 \text{ mA}$
OL.	Output LOW Voltage		2.7		0.2		$I_{OL} = 100 \mu A$
			2.7		0.5		I <sub>OL</sub> = 24 mA
			3.0		0.4	V	I <sub>OL</sub> = 16 mA
			3.0		0.5		I <sub>OL</sub> = 32 mA
			3.0		0.55		I <sub>OL</sub> = 64 mA
I(HOLD)	Bushold Input Minimum Drive		3.0	75		μА	$V_{I} = 0.8V$
Note 5)				-75		μΛ	$V_I = 2.0V$
I(OD)	Bushold Input Over-Driv	/e	3.0	500		μА	(Note 6)
Note 5)	Current to Change State	е		-500			(Note 7)
ı	Input Current		3.6		10		$V_{I} = 5.5V$
		Control Pins	3.6		±1	μА	$V_I = 0V$ or $V_{CC}$
		Data Pins	3.6		<del>-</del> 5	μΑ	$V_I = 0V$
		Data Filis	3.0		1		$V_I = V_{CC}$
OFF	Power Off Leakage Cur	rent	0		±100	μΑ	$0V \le V_I \text{ or } V_O \le 5.5V$
PU/PD	Power Up/Down 3-STA	ГЕ	0–1.5		±100	μА	$V_0 = 0.5V \text{ to } 3.0V$
	Output Current		0-1.5		±100	μА	$V_I = GND \text{ or } V_{CC}$
OZL	3-STATE Output Leakage Current		3.6		<b>-</b> 5	μΑ	V <sub>O</sub> = 0.5V
OZL (Note 5)	3-STATE Output Leakag	ge Current	3.6		<b>−</b> 5	μΑ	$V_0 = 0.0V$
OZH	3-STATE Output Leakage	ge Current	3.6		5	μΑ	V <sub>O</sub> = 3.0V

# DC Electrical Characteristics (Continued)

Symbol	Parameter		$V_{CC}$ $T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		°C to +85°C	Units	Conditions
Symbol			(V)	Min	Max	Omis	Conditions
I <sub>OZH</sub> (Note 5)	3-STATE Output Leakage	e Current	3.6		5	μΑ	V <sub>O</sub> = 3.6V
I <sub>OZH</sub> +	3-STATE Output Leakage	e Current	3.6		10	μΑ	$V_{CC} < V_O \le 5.5V$
I <sub>CCH</sub>	Power Supply Current	V <sub>CC1</sub> or V <sub>CC2</sub>	3.6		0.19	mA	Outputs HIGH
I <sub>CCL</sub>	Power Supply Current	V <sub>CC1</sub> or V <sub>CC2</sub>	3.6		5.0	mA	Outputs LOW
I <sub>CCZ</sub>	Power Supply Current	V <sub>CC1</sub> or V <sub>CC2</sub>	3.6		0.19	mA	Outputs Disabled
I <sub>CCZ</sub> +	Power Supply Current	V <sub>CC1</sub> or V <sub>CC2</sub>	3.6		0.19	mA	$V_{CC} \le V_O \le 5.5V$ ,
							Outputs Disabled
$\Delta I_{CC}$	Increase in Power Supply	y Current	3.6		0.2	mA	One Input at V <sub>CC</sub> – 0.6V
	(Note 8)	$V_{CC1}$ or $V_{CC2}$					Other Inputs at V <sub>CC</sub> or GND

Note 5: Applies to bushold versions only (74LVTH32245).

Note 6: An external driver must source at least the specified current to switch from LOW-to-HIGH.

Note 7: An external driver must sink at least the specified current to switch from HIGH-to-LOW.

 $\textbf{Note 8:} \ \text{This is the increase in supply current for each input that is at the specified voltage level rather than $V_{CC}$ or $GND$.}$ 

### **Dynamic Switching Characteristics** (Note 9)

					Miller Free		
Symbol	Parameter	v <sub>cc</sub>	V <sub>CC</sub> T <sub>A</sub> = 25°C		Units	Conditions	
Symbol	T drameter	(V)	Min	Тур Мах	Office	$C_L = 50 \text{ pF, } R_L = 500\Omega$	
V <sub>OLP</sub>	Quiet Output Maximum Dynamic V <sub>OL</sub>	3.3	20	0.8	V	(Note 10)	
Volv	Quiet Output Minimum Dynamic Vo	3.3	. 455/20	-0.8	V	(Note 10)	

Note 9: Characterized in SSOP package. Guaranteed parameter, but not tested

Note 10: Max number of outputs defined as (n). n–1 data inputs are driven 0V to 3V. Output under test held LOW.

#### **AC Electrical Characteristics**

Symbol	Parameter	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $C_L = 50 \text{ pF}, R_L = 500\Omega$				Units
		$V_{CC} = 3.3V \pm 0.3V$		V <sub>CC</sub> = 2.7V		Julius
		Min	Max	Min	Max	
t <sub>PLH</sub>	Propagation Delay Data to Output	1.5	3.5	1.5	3.9	20
t <sub>PHL</sub>		1.3	3.5	1.3	3.9	ns
t <sub>PZH</sub>	Output Enable Time	1.5	4.5	1.5	5.3	20
$t_{PZL}$		1.6	5.3	1.6	6.9	ns
t <sub>PHZ</sub>	Output Disable Time	2.3	5.4	2.3	6.1	ns
$t_{PLZ}$		2.2	5.1	2.2	5.4	115

### Capacitance (Note 11)

Symbol	Parameter	Conditions	Typical	Units
C <sub>IN</sub>	Input Capacitance	$V_{CC} = 0V$ , $V_I = 0V$ or $V_{CC}$	4	pF
C <sub>I/O</sub>	Input/Output Capacitance	$V_{CC} = 3.0V$ , $V_O = 0V$ or $V_{CC}$	8	pF

Note 11: Capacitance is measured at frequency f = 1 MHz, per MIL-STD-883, Method 3012.

# Physical Dimensions inches (millimeters) unless otherwise noted ○ 0.10 B 5.5 0.4 (0.75) 0.10 A ABCDEFGHJKLMNPR 0.4 13.5 12 PIN ONE 0.8 96X 0.5<sup>+0.05</sup> Top 0.15(M) C A B Bottom View View 0.08(M) C ATING PLANE // 0.15 C 1.4 MAX 0.10 NOTES: A. THIS PACKAGE CONFORMS TO JEDEC M0-205 B. ALL DIMENSIONS IN MILLIMETERS C. LAND PATTERN RECOMMENDATION: NSMD (Non Solder Mask Defined) 35MM DIA PADS WITH A SOLDERMASK OPENING OF .45MM CONCENTRIC TO PADS D. DRAWING CONFORMS TO ASME Y14.5M-1994 BGA96ArevE 96-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide Package Number BGA96A

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